L Number	Hits	Search Text	DB	Time stamp
1	1	("6559537").PN.	USPAT	2003/09/18 11:06
2	13720	((heat adj (sink or dissipation or dissipate)) or (thermally adj conductive)) with (case or container or package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 11:12
3	6081	(((heat adj (sink or dissipation or dissipate)) or (thermally adj conductive)) with (case or container or package)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 11:08
4	4450	((((heat adj (sink or dissipation or dissipate)) or (thermally adj conductive)) with (case or container or package)) and (chip or die)) and ((chip or die) with (case or container or package))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 11:09
5	3207	(((((heat adj (sink or dissipation or dissipate)) or (thermally adj conductive)) with (case or container or package)) and (chip or die)) and ((chip or die) with (case or container or package)) and (@ad<20000905)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 11:13
6	2469	((((((heat adj (sink or dissipation or dissipate)) or (thermally adj conductive)) with (case or container or package)) and (chip or die)) and ((chip or die) with (case or container or package))) and (@ad<20000905)) and (((heat adj (sink or dissipation or dissipate)) or (thermally adj conductive)) with (chip or die))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 11:11
7	217	257/704.ccls. and ((heat adj (sink or dissipation or dissipate)) or (thermally adj conductive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 11:12
8	186	(257/704.ccls. and ((heat adj (sink or dissipation or dissipate)) or (thermally adj conductive))) and (@ad<20000905)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 11:37
9	2	(("6191360") or ("6457506")).PN.	USPAT	2003/09/18 11:42
10	2	(("5321222") or ("5521360")).PN.	USPAT	2003/09/18 11:46
11	0	epxy near rubber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 11:49
12	1967	epoxy near rubber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 11:52
13	196	(cure or curing) with (epoxy and microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 11:53
14	124	((cure or curing) with (epoxy and microwave)) and (@ad<19991230)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 12:27

15	41	(((cure or curing) with (epoxy and microwave)) and (@ad<19991230)) and (chip or die or (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 12:04
16	4	((((cure or curing) with (epoxy and microwave)) and (@ad<19991230)) and (chip or die or (integrated adj circuit))) and bake	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 12:10
17	0	(((cure or curing) with (epoxy and microwave)) and (@ad<19991230)) and (bake with (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 12:11
18	741	(chip or die) and (bake with (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 12:25
19	115	((chip or die) and (bake with (substrate or wafer))) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 12:11
20	51	(((chip or die) and (bake with (substrate or wafer))) and package) and (@ad<19991230)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 12:12
21	13	((((chip or die) and (bake with (substrate or wafer))) and package) and (@ad<19991230)) and cure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 12:17
22	38	((((chip or die) and (bake with (substrate or wafer))) and package) and (@ad<19991230)) not (((((chip or die) and (bake with (substrate or wafer))) and package) and (@ad<19991230)) and cure)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 12:17
23	0	(chip or die) and (bake near PCB)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 12:25
24	4	(chip or die) and (bake with PCB)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 12:26
25	1	(chip or die) and ((bake and substrate) same PCB)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 12:27
26	13	((bake and substrate) same PCB)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 12:27
27	9	(((bake and substrate) same PCB)) and (@ad<19991230)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 12:28